

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of: M.H. McKerregan et al. Date: March 25, 2009  
Application No.: 10/536,859 Examiner: N.W. Ha  
Filing Date: June 26, 2006 Group Art Unit: 2814  
Title: PACKAGE HAVING EXPOSED INTEGRATED  
CIRCUIT DEVICE

**Mail Stop Issue Fee**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**SUBMISSION OF FOREIGN PATENT DOCUMENT**

Sir:

Further to the Information Disclosure Statement filed in this application on March 16, 2009, and in compliance with 37 C.F.R. § 1.98(a)(2)(i), a copy of Taiwan patent document TW 501246 is submitted herewith.

This document was cited in an office action in a counterpart foreign application, and listed on the Information Disclosure Statement (form PTO/SB/08a) filed on March 16, 2009.

**CERTIFICATE OF MAILING OR TRANSMISSION (37 C.F.R. § 1.8(a))**

I hereby certify that this correspondence (along with any paper referred to as being attached or enclosed) is being:

- ☐ deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.
- ☐ transmitted by facsimile on the date shown below to the United States Patent and Trademark Office at (571) 273-8300.
- ☒ transmitted via the electronic filing system of the United States Patent and Trademark Office on the date shown below and in accordance with 37 C.F.R. § 1.6(a)(4).

March 25, 2009

Signed: \_\_\_\_\_

Jay H. Anderson



It is noted that the cited foreign patent document is not in the English language. A concise explanation of the relevance thereof, as required by 37 C.F.R. § 1.98(a)(3)(i), is as follows: The reference describes a process including providing a semiconductor wafer, wherein a plurality of chips are formed thereon and a plurality of bonding pads are formed on the central area of the chip; cutting adjacent chips so as to form a recess on the edge of a second surface and a recess on the edge of a first surface of each chip; cutting the wafer so as to form a plurality of single chips; forming a solder on each bonding pad; and encapsulating the chip and the recesses with resin.

The applicants respectfully request that this reference be made of record in the present application.

The applicants' undersigned attorney may be reached by telephone at 212-551-2625. All correspondence should continue to be directed to the address given below, which is the address associated with Customer Number 27267.

Respectfully submitted,



Jay H. Anderson  
Registration Number 38,371  
Attorney for Applicants  
Tel: (212) 551-2625  
Fax: (212) 490-0536

WIGGIN AND DANA LLP  
450 Lexington Avenue, Suite 3800  
New York, NY 10017

Date: March 25, 2009

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